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METHOD AND APPARATUS FOR FLIP-CHIP PACKAGING PROVIDING TESTING CAPABILITY

ABSTRACT

A method and apparatus for increasing the integrated circuit density in a flip chip semiconductor device assembly including an interposer substrate facilitating use with various semiconductor die conductive bump arrangements. The interposer substrate includes a plurality of recesses formed in at least one of a first surface and a second surface of the interposer substrate, wherein the recesses are arranged in a plurality of recess patterns. The interposer substrate also provides enhanced accessibility for test probes for electrical testing of the resulting flip chip semiconductor device assembly.

[Figure 2]